

PATENT ABSTRACTS OF JAPAN

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(54) PROBE BOARD

(57)Abstract:

PURPOSE: To simplify assembling and to make signal transmission excellent by constructing a probe assembly by fitting functions, and by fitting the probe assembly to a wiring board so that it corresponds to an electrode on one or a plurality of sides of a semiconductor device.

CONSTITUTION: A wiring means opposed to an electrode provided on one side of a semiconductor device is formed on a flexible wiring board, a probe of which the connecting end side is connected electrically to the wiring means and of which the fore end part is aligned with an electrode to be measured is provided, and a guide part into which the probe is inserted is provided in a film so designed as to hold the probe with the flexible wiring board, between them. A laminated structure thus constructed is fitted on the lower surface of a probe fitting body in such a manner that it is pressed from the lower surface side by a clamping plate, while an elastic body for giving a spring property to the fore end of the probe is interposed therebetween, and thereby a probe assembly is constructed. One or a plurality of probe assemblies so provided as to correspond to the electrode on one or a plurality of sides of the semiconductor device are fitted to the wiring board.

